

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4991371

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SHIJIE CHEN	05/30/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Silergy Semiconductor Technology (Hangzhou) LTD.
<b>Street Address:</b>	A1501 Technology Mansion, No. 90 Wensan Road
<b>City:</b>	Hangzhou, ZheJiang Province
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	310012
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15997846
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	SILG2017P26US
<b>NAME OF SUBMITTER:</b>	MICHAEL C. STEPHENS, JR.
<b>SIGNATURE:</b>	/Michael C. Stephens, Jr./
<b>DATE SIGNED:</b>	06/05/2018
<b>Total Attachments: 2</b>	
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ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, the person(s) named below (referred herein as "INVENTOR" whether singular or plural) has sold, assigned, and transferred and does hereby sell, assign, and transfer to **SILERGY SEMICONDUCTOR TECHNOLOGY (HANGZHOU) LTD.**, having a place of business at A1501 Technology Mansion, No. 90 Wensan Road, Hangzhou, ZheJiang Province, China 310012 ("ASSIGNEE"), for itself and its successors, transferees, and assignees, the following:

1. The entire worldwide right, title, and interest in all inventions and improvements ("SUBJECT MATTER") that are disclosed in the provisional application filed under 35 U.S.C. §111(b) or non-provisional application filed under 35 U.S.C. §111(a) and entitled CHIP PACKAGING METHOD AND PACKAGE STRUCTURE ("APPLICATION"), which:

was filed on 6/5/18, now bearing U.S. serial number 15/997,826; and

2. The entire worldwide right, title, and interest in and to:  
(a) the APPLICATION; (b) all applications claiming priority from the APPLICATION; (c) all divisional, continuation, substitute, renewal, reissue, and other related applications thereto which have been or may be filed in the United States or elsewhere in the world; (d) all patents (including reissues and re-examinations) which may be granted on the applications set forth in (a), (b), (c) and (d) above; and (e) all right of priority in the APPLICATION, together with all rights to recover damages for infringement of provisional rights.

INVENTOR agrees that ASSIGNEE may apply for and receive patents for SUBJECT MATTER in ASSIGNEE's own name.

INVENTOR agrees to do the following, when requested, and without further consideration, in order to carry out the intent of this Assignment: (1) execute all assignments, oaths, powers of attorney, applications, and other papers (and/or documents) necessary or desirable to fully secure to ASSIGNEE the rights, titles and interests herein conveyed; (2) communicate to ASSIGNEE all known facts relating to the SUBJECT MATTER; and (3) generally do all lawful acts that ASSIGNEE shall consider desirable for securing, maintaining, and enforcing worldwide patent protection relating to the SUBJECT MATTER and for vesting in ASSIGNEE the rights, titles, and interests herein conveyed. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE hereunder.

INVENTOR represents that INVENTOR has the rights, titles, and interests to convey as set forth herein, and covenants with ASSIGNEE that the INVENTOR has not made and will not hereafter make any assignment, grant, mortgage, license, or other agreement affecting the rights, titles, and interests herein conveyed.

INVENTOR grants the attorney(s) of record the power to insert on this Assignment any further identification, including an application serial number and filing date, as may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Title of Document: ASSIGNMENT

Re:

Title: CHIP PACKAGING METHOD AND PACKAGE STRUCTURE

Filed: (if applicable) 06/05/2018

Atty. Docket No.: SILG2017P26US

Serial No.: (if applicable) 15/997,846

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This Assignment may be executed in one or more counterparts, each of which shall be deemed an original and all of which may be taken together as one and the same Assignment.

Name and Signature

Date of Signature

Shijie Chen  
Shijie Chen

5/30/2018